



CQFN Package

Ceramic QFN

For High Temperature Use

◆ DESCRIPTION

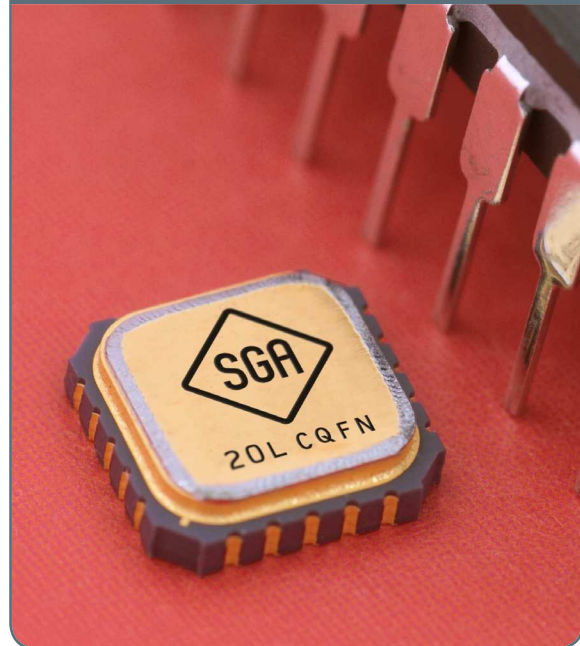
The CQFN packages from SGA are miniature hermetic ceramic packages specifically designed for high temperature applications using ceramic substrates.

The package lid is seam welded to the seal ring to create an hermetic package that will withstand high temperature soldering processes.

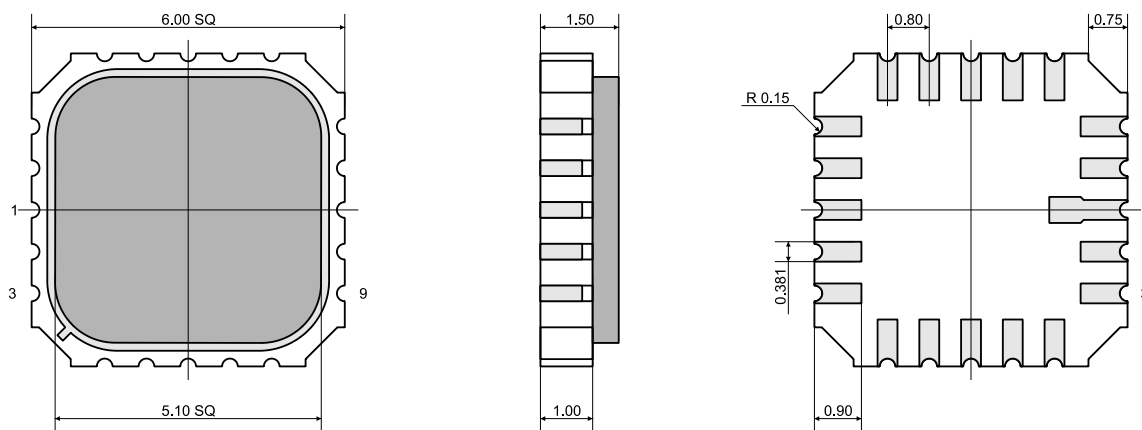
The 20L CQFN footprint is equivalent to a 20 pin QFN plastic package.

Lead pitch	0.8 mm
Outer dimension	6.0 mm square
Package height	1.5 mm

◆ OVERVIEW



◆ 20L CQFN MECHANICAL DIMENSIONS



□ Au/Ni plating □ Kovar seal ring and lid

Seal ring and lid connected to pin 9
Footprint equivalent to 20L QFN according to JEDEC MO-220 VJJB



◆ SALES CONTACT

***Please visit our website www.sga.se
for more information about our
representatives and distributors,
or contact SGA directly.***

specific 
components

Svenska Grindmatriser AB
Brigadgatan 16
SE-587 58 Linköping
Sweden

Phone: +46 13 36 46 60
Fax: +46 13 36 46 61
E-mail: info@sga.se
www.sga.se

◆ INFORMATION

Additional information and support

If you need any technical advice or help in any way regarding this product, please send an E-mail to support@sga.se, or call SGA, +46 13 364660, and ask for support. We will always be pleased to discuss your requirements and how this product could be used in your application.

Electrostatic discharge (ESD) precautions

Electrostatic Discharge (ESD) can damage this integrated circuit. SGA recommends that all integrated circuits is handled with appropriate precautions. Failure to observe proper handling may cause performance degradation or complete failure.

Data sheet identification

Advance Information

The product is in a formative or design stage. The data sheet contains target specifications for product development. Engineering samples may or may not be available.

Preliminary Specification

The data sheet contains preliminary data. Additional data may be added later. Engineering samples are available. Production quantities may or may not be available.

Product Specification

The data sheet contains final product specifications. The product is in full production.

Notice

Svenska Grindmatriser AB (SGA) believes the information contained in this data sheet to be correct and accurate at the time of printing. However, SGA assumes no liability for the use of this information. Use shall be entirely at the user's own risk.

Svenska Grindmatriser AB (SGA) reserves the right to make changes without further notice to the product to improve reliability, function or design. SGA does not assume any liability arising out of the application or use of any product or circuits described herein.

© 2009 Svenska Grindmatriser AB.
All rights reserved